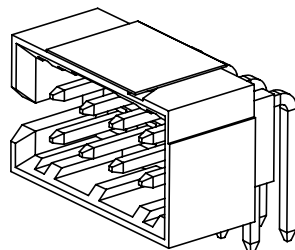
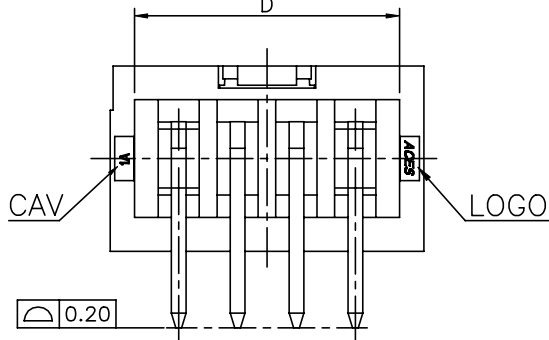
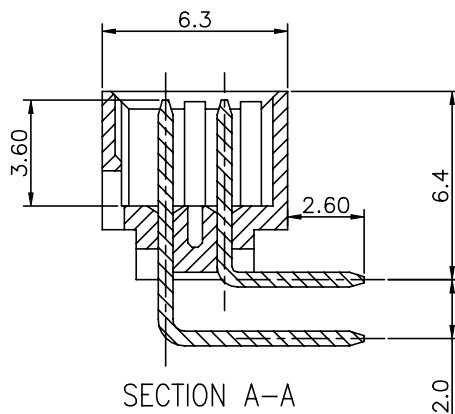
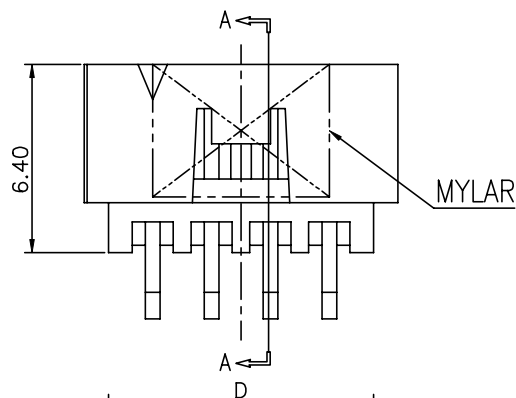


RECOMMENDED PCB LAYOUT
GENERAL TOLERANCE ± 0.05



NOTES:

1. MATERIAL:
 - 1.1 HOUSING: THERMOPLASTIC, HIGH TEMP., UL94V-0; COLOR:BLACK
 - 1.2 TERMINAL: COPPER ALLOY
2. FINISH: UNDERPLATING: 50~100u" NICKEL OVERALL.
 - 2.1 CONTACT AREA:
 - 1: G/F
 - C: GOLD 15u"
 - N: 80u" MIN MATTE TIN
 - 2.2 SOLDER AREA: MATTE TIN
3. REFLOW SOLDER CAPABLE TO 260°C PER ACES SPEC.
4. SPEC. PLS. REFER TO PS-51352-XXXX-XXX
5. PART NUMBER

51352-XXX	X	X-XXX	XXX	CENTER LOCK	COLOR
CKTS			001	Y	BLACK

PACKING

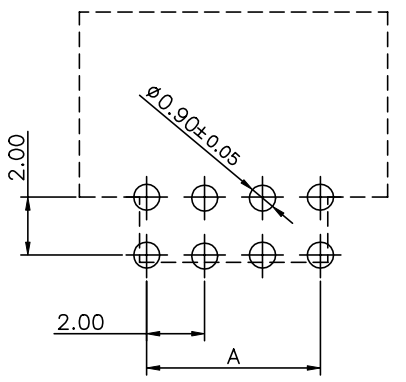
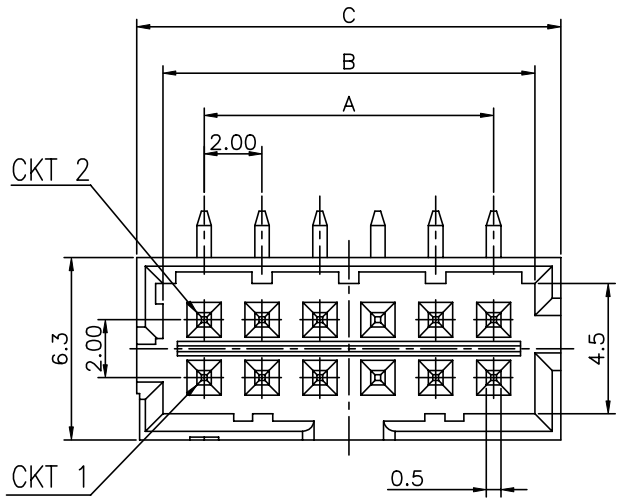
PLATING

- 1.TUBE
- 5.TUBE WITH MYLAR

- C: GOLD 15u" ON CONTACT,
MATTE TIN ON SOLDER
- 1: G/F
N:MATTE TIN

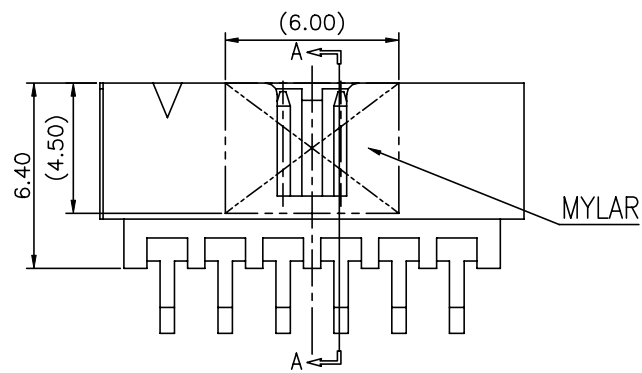
CKT	DIM A	DIM B	DIM C	DIM D
8	6.00	8.85	10.65	9.00

QUALITY SYMBOLS MAJOR CRITICAL GENERAL TOLERANCES (UNLESS SPECIFIED) X. ± 0.5 X ± 0.25 .XX ± 0.15 .XXX ± 0.1 ANGLES $\pm 2^\circ$	DRAWN BY Huang,ShunSen CHECKED BY Lu, jing quan APPROVED BY hsieh,fu yu	DATE 23/10/13 DATE 23/10/13 DATE 23/10/13	 ACES ELECTRONICS TITLE 2.0mm WTB WAFER CONN T/H D/R R/A TYPE. SIZE A4 RFG NO. NA SHEET NO. 1 OF 3 DWG NO. 51352-XXXX-XXX	
	UNITS mm			SCALE 1:1
	SCALE 1:1	SHEET NO. 1 OF 3		DWG NO. 51352-XXXX-XXX
	UNITS mm			SCALE 1:1



RECOMMENDED PCB LAYOUT
GENERAL TOLERANCE ± 0.05

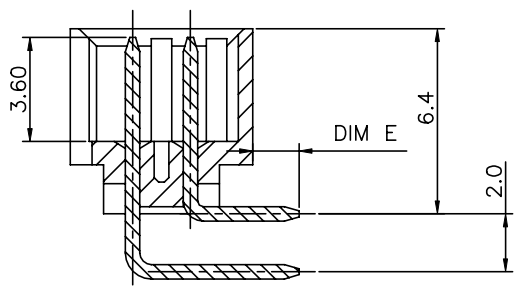
- NOTES:
- MATERIAL:
 - HOUSING: THERMOPLASTIC, HIGH TEMP., UL94V-0; COLOR:BLACK
 - TERMINAL: COPPER ALLOY
 - FINISH: UNDERPLATING: 50~100u" NICKEL OVERALL.
 - CONTACT AREA:
 - G/F
 - GOLD 15u"
 - 80U" MIN MATTE TIN
 - SOLDER AREA: MATTE TIN
 - REFLOW SOLDER CAPABLE TO 260°C PER ACES SPEC.
 - SPEC. PLS. REFER TO PS-51352-XXXX-XXX
 - PART NUMBER



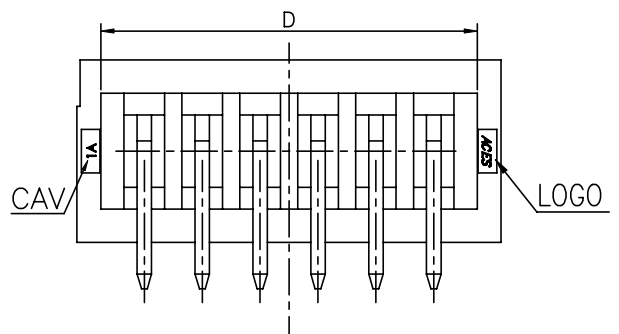
51352-XXX	X	X-XXX	XXX	CENTER LOCK	COLOR	PACKING	DIM E
CKT			002	N	BLACK	51352-XXXXX-00-TRP	1.6
			003	N	BLACK	51352-XXXXX-05-TRP	2.16

PACKING
4:T&R WITH MYLAR
5.TUBE WITH MYLAR

PLATING
C:GOLD 15u" ON CONTACT
MATTE TIN ON SOLDER
1: G/F
N:MATTE TIN

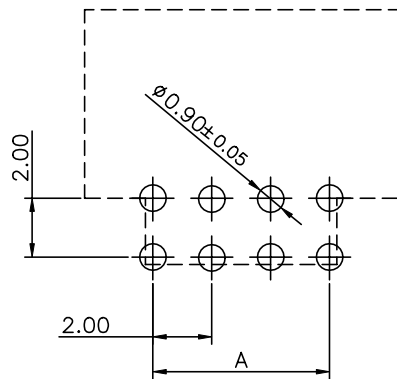
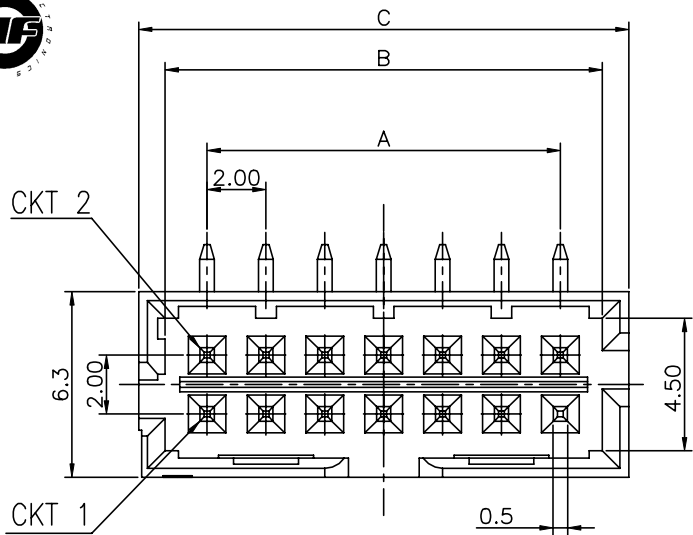


SECTION A-A



CKT	DIM A	DIM B	DIM C	DIM D
8	6.00	8.85	10.65	9.00
12	10.00	12.85	14.65	13.00

QUALITY SYMBOLS MAJOR CRITICAL GENERAL TOLERANCES (UNLESS SPECIFIED) X ± 0.5 .X ± 0.25 .XX ± 0.15 .XXX ± 0.1 ANGLES $\pm 2'$	DRAWN BY Huang,ShunSen 23/10/13	DATE 23/10/13		
	CHECKED BY Lu, jing quan 23/10/13	DATE 23/10/13		TITLE 2.0mm WTB WAFER CONN T/H D/R R/A TYPE.
	UNITS mm		SIZE A4	RFQ NO. NA
	SCALE 1:1	SHEET NO. 2 OF 3	REV E	DWG NO. 51352-XXXXX-XXX



RECOMMENDED PCB LAYOUT
GENERAL TOLERANCE ± 0.05

NOTES:

1. MATERIAL:
 - 1.1 HOUSING: THERMOPLASTIC, HIGH TEMP., UL94V-0; COLOR BLACK
 - 1.2 TERMINAL: COPPER ALLOY
2. FINISH: UNDERPLATING: 50~100u" NICKEL OVERALL.
 - 2.1 CONTACT AREA:
 - 1: G/F
 - C: GOLD 15u"
 - N: 80U" MIN MATTE TIN
 - 2.2 SOLDER AREA: MATTE TIN
3. REFLOW SOLDER CAPABLE TO 260°C PER ACES SPEC.
4. SPEC. PLS. REFER TO PS-51352-XXXXX-XXX
5. PART NUMBER

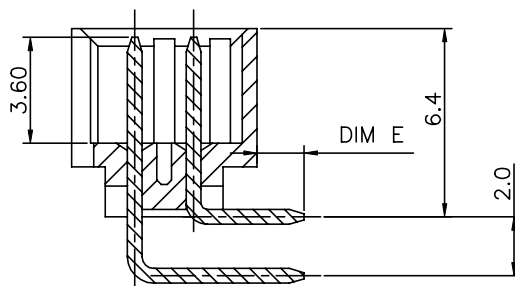
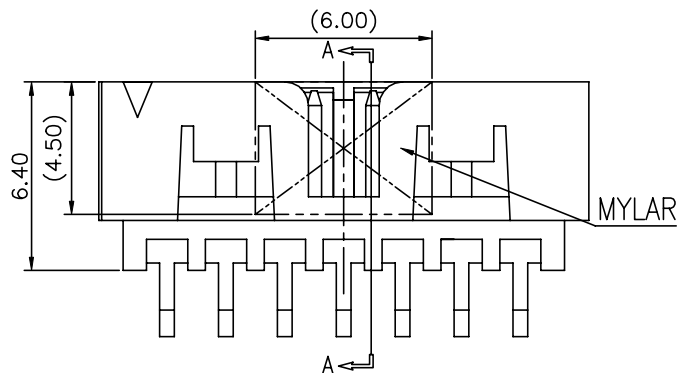
51352-XXX X X-XXX

CKT

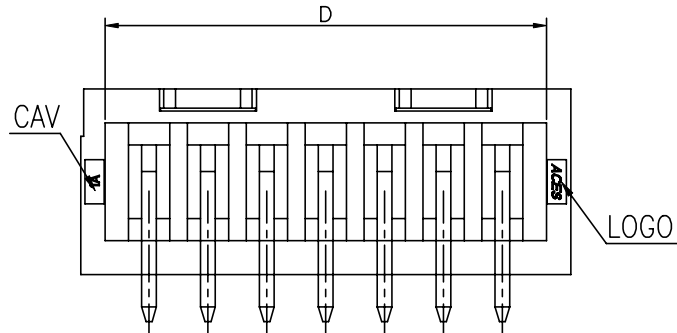
PACKING
4:T&R WITH MYLAR
5:TUBE WITH MYLAR

XXX	CENTER LOCK	COLOR	PACKING	DIM E
001	N	BLACK	51352-XXXXX-07-TRP	2.6
002	N	BLACK	51352-XXXXX-00-TRP	1.6
003	N	BLACK	51352-XXXXX-05-TRP	2.16

PLATING
C:GOLD 15u" ON CONTACT
MATTE TIN ON SOLDER
1: G/F
N:MATTE TIN



SECTION A-A



CKT	DIM A	DIM B	DIM C	DIM D
14	12.00	14.85	16.65	15.00

QUALITY SYMBOLS MAJOR CRITICAL GENERAL TOLERANCES (UNLESS SPECIFIED) X ± 0.5 .X ± 0.25 .XX ± 0.15 .XXX ± 0.1 ANGLES $\pm 2^\circ$	DRAWN BY Huang,ShunSen CHECKED BY Lu, jing qian APPROVED BY hsieh,tu yu	DATE 23/10/13 DATE 23/10/13 DATE 23/10/13	 2.0mm WTB WAFER CONN T/H D/R R/A TYPE.		
	UNITS mm			SIZE A4	RFQ NO. NA
	SCALE 1:1	SHEET NO. 3 OF 3		REV E	DWG NO. 51352-XXXXX-XXX